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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/517,948	09/26/2005	Andreas Heise	AP 10454	7242
<div>7590      01/31/2008</div> <div>Gerlinde Nattler Continental Teves Inc One Continental Drive Auburn Hills, MI 48326</div>				
			EXAMINER CHEN, XIAOLIANG	
			ART UNIT 2841	PAPER NUMBER
			MAIL DATE 01/31/2008	DELIVERY MODE PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

## Office Action Summary

Application No.

10/517,948

Applicant(s)

HEISE ET AL.

Examiner

Xiaoliang Chen

Art Unit

2841

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1) ☒ Responsive to communication(s) filed on 15 January 2008.
- 2a) ☒ This action is **FINAL**.                      2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

### Disposition of Claims

- 4) ☒ Claim(s) 11-20 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 11-20 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \*    c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

### Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)  
Paper No(s)/Mail Date \_\_\_\_\_
- 4) ☐ Interview Summary (PTO-413)  
Paper No(s)/Mail Date. \_\_\_\_\_
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: \_\_\_\_\_

## DETAILED ACTION

### *Response to Arguments*

1. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

### *Claim Rejections - 35 USC § 103*

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

3. Claims 11-15 and 18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Krueger et al. (US6043966) in view of Rottenberg et al. (US20030149456).

**Re claim 11**, Krueger et al. clearly show and disclose

A printed circuit board (15, fig. 1) comprising strip conductors (25, fig. 1) for electronic circuits and connections (a printed circuit board having a plurality of conductive traces deposited on a surface [ABSTRACT]) for a voltage supply unit (an electrical assembly 10 [col. 3, line 34]; fig. 1, a voltage supply or power supply is very a common unit, and an electrical assembly inherently could be or could be connected for a voltage supply) being equipped with at least one SMD-component (surface-mounted, electronic components [col. 1, line 32]) and additional parts (additional electrical components [col. 3, line 23]) that are soldered in a suitable manner (fig. 1), said voltage supply unit being connected to at least one supplying strip conductor (conductive layer 135 is deposited on the substrate 87 connecting the first and second circuit traces 125,130 [col. 4, line 32]),

Krueger et al. does not disclose

wherein at least one of the supplying strip conductors includes a break which is bridged in a conductive manner by means of a fuse bridge, said fuse bridge consisting of a basic material, the melting point of which is lower than the melting point of the material of which the strip conductors are made.

Rottenberg et al. disclose a device wherein

at least one of the supplying strip conductors includes a break (64, fig. 3C) which is bridged in a conductive manner by means of a fuse bridge (51', fig. 3C), said fuse bridge consisting of a basic material (metal conductor 62, [0056], fig. 3C), the melting point of which is lower than the melting point of the material of which the strip conductors (metal conductors 60a and 60b [0056]) are made. (the metal conductor 62 fuses to form a bridge to the strip conductors. The metal conductor 62 is formed of a metal having a low melting point. The lower temperature should be much less than the melting point of the strip conductors. [0056])

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the fuse bridge of Krueger et al. by using a lower melting point metal conductor as taught by Rottenberg et al., in order to manufacture a lower melting point fuse which provides better protection control.

**Re claim 12,** Krueger et al. clearly show and disclose

The printed circuit board as claimed in claim 11, wherein the melting point of the basic material is at least as high as the melting point of the solder (the melting point of tin or a tin/lead alloy is higher than the melting point of solder) used for placement of the printed circuit board.

**Re claim 13,** Krueger et al. clearly show and disclose

The printed circuit board as claimed in claim 11, wherein the fuse bridge fully consists of metallic material (tin or a tin/lead alloy is applied to the thin fusible elements 136 forming fusible links 139 [col.4, line 64]).

**Re claim 14**, Krueger et al. clearly show and disclose

The printed circuit board as claimed in claim 13, wherein the metallic material comprises tin or any tin alloy (tin or a tin/lead alloy is applied to the thin fusible elements 136 forming fusible links 139 [col.4, line 64]).

**Re claim 15**, Krueger et al. clearly show and disclose

The printed circuit board as claimed in claim 11, wherein the fuse bridge is connected to material of the strip conductor in a conductive fashion by means of the solder used in the soldering process (These discrete surfaced-mounted electronic components are typically soldered or electrically connected to the conductive traces [col. 1, line 34]).

**Re claim 18**, Krueger et al. clearly show and disclose

The printed circuit board as claimed in claim 11, wherein the basic material for manufacturing the fuse bridge is coated with a layer (a second conductive layer is applied to the first conductive layer to form a fusible link [col. 2, line 19]) made of a material out of the group consisting of tin (tin [col.4, line 64]), any tin alloy (tin/lead alloy [col.4, line 64]), gold and passivated copper (electroless plated copper [col. 5, line 23]).

4. Claims 16-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Krueger et al. in view of Rottenberg et al. as applied to claim 11 above, and further in view of Montgomery et al. (US6034589).

**Re claim 16**, Krueger et al. and Rottenberg et al. disclose

The printed circuit board as claimed in claim 11,

Krueger et al. and Rottenberg et al. do not disclose the fuse bridge being shaped in such a way that it can be fed to a conventional pick-and-place machine in a taped and magazined fashion.

Montgomery et al. teaches a device wherein

the fuse bridge is shaped in such a way that it can be fed to a conventional pick-and-place machine (the use of surface mount components generally lowers manufacturing costs by allowing the use of highly automated assembly equipment [col. 1, line 20]) in a taped and magazined fashion (taped and magazined is a well known package in the art of surface mount components and a common fashion for the surface mount components used in the highly automated assembly equipment).

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the fuse bridge of Krueger et al. and Rottenberg et al. with the same shape as taught by Montgomery et al., in order to "low manufacturing costs by allowing the use of highly automated assembly equipment." (Montgomery et al., col. 1, line 20)

**Re claim 17**, Krueger et al. and Rottenberg et al. disclose

The printed circuit board as claimed in claim 11,

Krueger et al. and Rottenberg et al. do not disclose the fuse bridge being manufactured by severing from a wire (fusible elements may comprise wires [col. 5, line 44]) or a sheet-metal strip.

In the same field of wiring board with fuse, Montgomery et al. teaches the following:

wherein the fuse bridge is manufactured by severing from a wire (fusible elements may comprise wires [col. 5, line 44]) or a sheet-metal strip.

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the fuse bridge of Krueger et al. and Rottenberg et al. with the wire as taught by Montgomery et al., since Montgomery et al. states in [col. 1, line 25], "in great demands for smaller, higher reliability, less costly fuses with greater amperage and voltage ratings."

5. Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krueger et al. in view of Rottenberg et al. as applied to claim 11 above, and further in view of Peter (US6314789).

**Re claim 19**, Krueger et al. and Rottenberg et al. disclose

The printed circuit board as claimed in claim 11,

Krueger et al. and Rottenberg et al. do not disclose adjacent supplying strip conductors being separated from each other by recesses.

Peter teaches a device wherein adjacent supplying strip conductors are separated from each other by recesses (cutout 20 [col. 3, line 19], fig. 1)

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to separate the strip conductors of Krueger et al. and Rottenberg et al. with the cutout as taught by Peter, since Peter states in [col. 1, line 50], "The heat barrier prevents thermal "cross-talk" between the support elements, so that the first heat source cooperates only with the first sensor element, and the second heat source cooperates only with the second sensor element, i.e., the heat barrier creates a thermal isolation between the two sensor elements and between respective sensor element and the heat source not assigned to that sensor element."

6. Claim 20 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krueger et al. in view of Rottenberg et al. and Montgomery et al.

**Re claim 20,** Krueger et al. show and disclose

A method of manufacturing a printed circuit board (15, fig. 1) comprising strip conductors (25, fig. 1) for electronic circuits and connections (a printed circuit board having a plurality of conductive traces deposited on a surface [ABSTRACT]) for a voltage supply unit (an electrical assembly 10 [col. 3, line 34], fig. 1, a voltage supply or power supply is very a common unit, and an electrical assembly inherently could be or could be connected for a voltage supply) being equipped with at least one SMD-component (surface-mounted, electronic

components [col. 1, line 32]) and additional electronic and/or electromechanical parts that (additional electrical components [col. 3, line 23]) are soldered in a suitable manner (fig. 1), said voltage supply unit being connected to at least one supplying strip conductor (conductive layer 135 is deposited on the substrate 87 connecting the first and second circuit traces 125,130 [col. 4, line 32]),

Krueger et al. does not disclose

wherein at least one of the supplying strip conductors includes a break which is bridged in a conductive manner by means of a fuse bridge, said fuse bridge consisting of a basic material, the melting point of which is lower than the melting point of the material of which the strip conductors are made.

Rottenberg et al. disclose a device wherein

at least one of the supplying strip conductors includes a break (64, fig. 3C) which is bridged in a conductive manner by means of a fuse bridge (51', fig. 3C), said fuse bridge consisting of a basic material (metal conductor 62, [0056], fig. 3C), the melting point of which is lower than the melting point of the material of which the strip conductors (metal conductors 60a and 60b [0056]) are made. (the metal conductor 62 fuses to form a bridge to the strip conductors. The metal conductor 62 is formed of a metal having a low melting point. The lower temperature should be much less than the melting point of the strip conductors. [0056])

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the fuse bridge of Krueger et al.

by using a lower melting point metal conductor as taught by Rottenberg et al., in order to manufacture a lower melting point fuse which provides better protection control.

Krueger et al. does not disclose the method comprising the step of manufacturing the fuse bridge immediately prior to placement of the printed circuit board.

Montgomery et al. teaches a device wherein the method comprising the step of manufacturing the fuse bridge immediately prior to placement of the printed circuit board (because a surface mount chip fuse 10 [col. 4, line 67], which is solder to a printed circuit board, it could be manufactured before mounting to the printed circuit board).

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the step of manufacturing the fuse bridge of Krueger et al. by immediately prior to placement of the printed circuit board as taught by Montgomery et al., in order to "provide a surface mount chip fuse which can be easily manufactured at low cost." (Montgomery et al., col. 2, line 65)

### ***Conclusion***

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Xiaoliang Chen whose telephone number is 571-272-9079. The examiner can normally be reached on 7:00-5:00 (EST), Monday-Thursday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Diego Gutierrez can be reached on 571-272-2245. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Xiaoliang Chen XC  
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